

# SOT2064-1

TBGA306, thin ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.91 mm body, molded array

28 January 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TBGA306
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-01-2021
<b>Manufacturer package code</b>	98ASA01587D

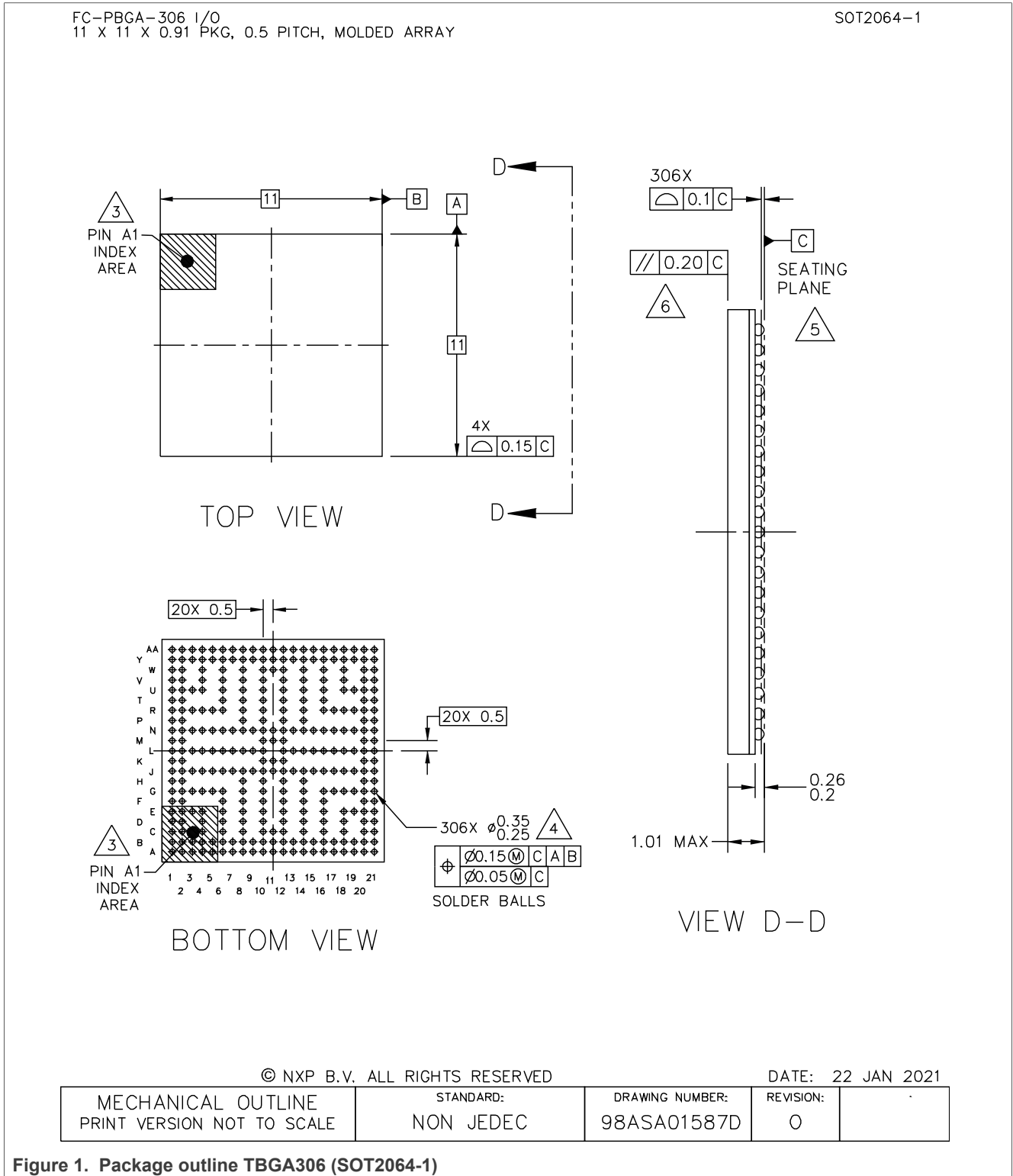
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.85	11	11.15	mm
package width	10.85	11	11.15	mm
seated height	-	0.91	1.01	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	306	-	



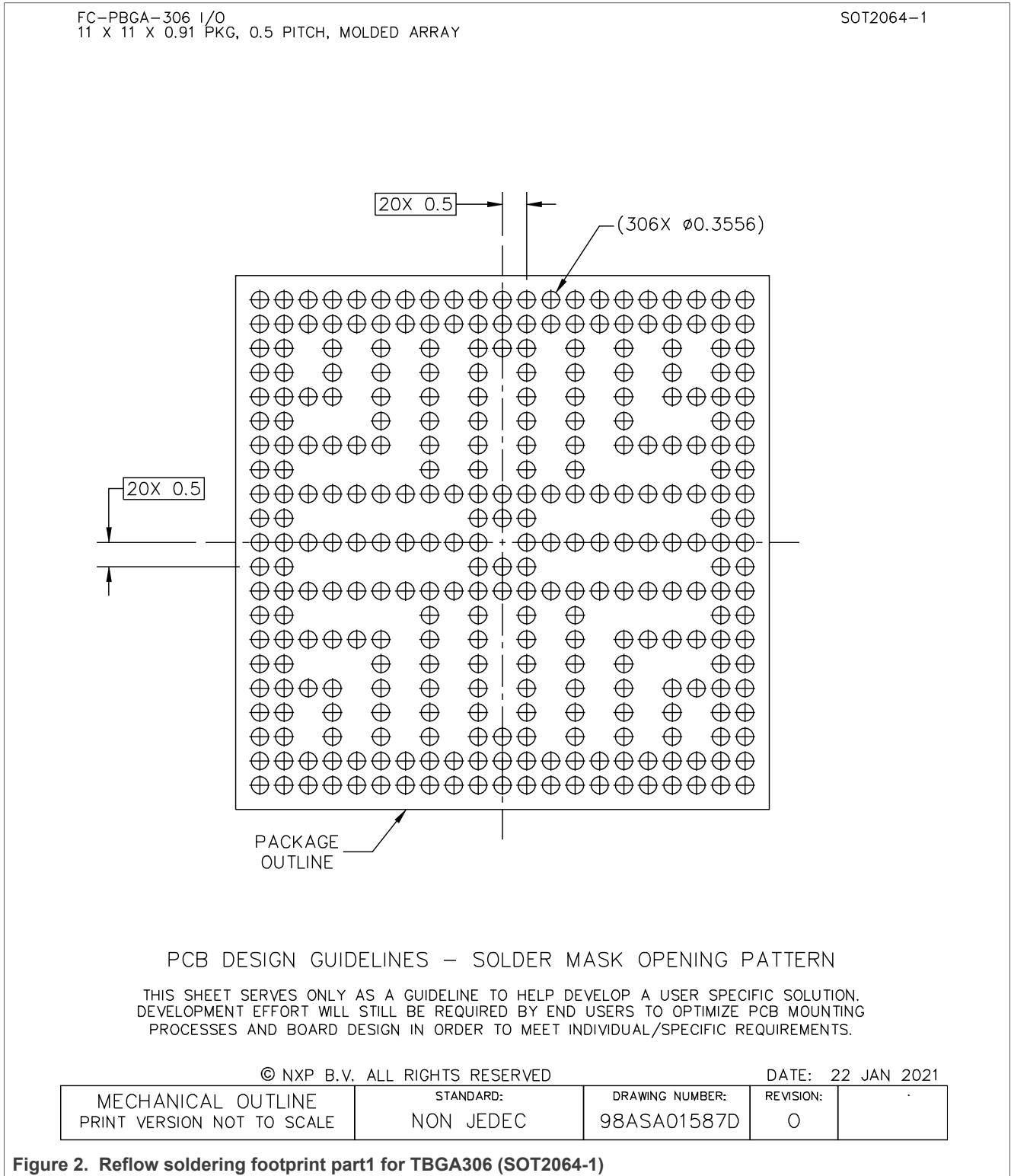
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2 Package outline



TBGA306, thin ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.91 mm body, molded array

3 Soldering



TBGA306, thin ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.91 mm body, molded array

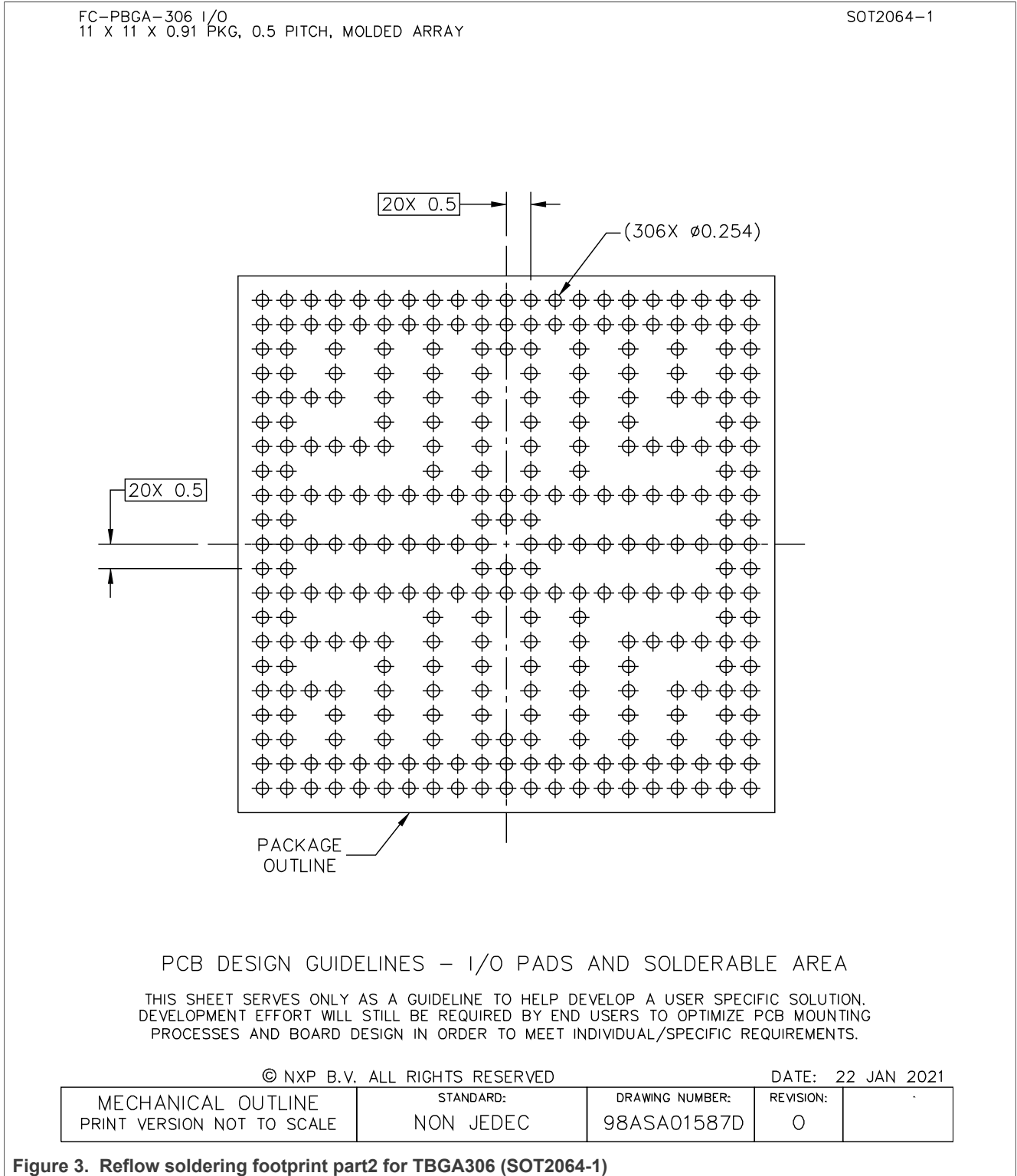


Figure 3. Reflow soldering footprint part2 for TBGA306 (SOT2064-1)

TBGA306, thin ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.91 mm body, molded array

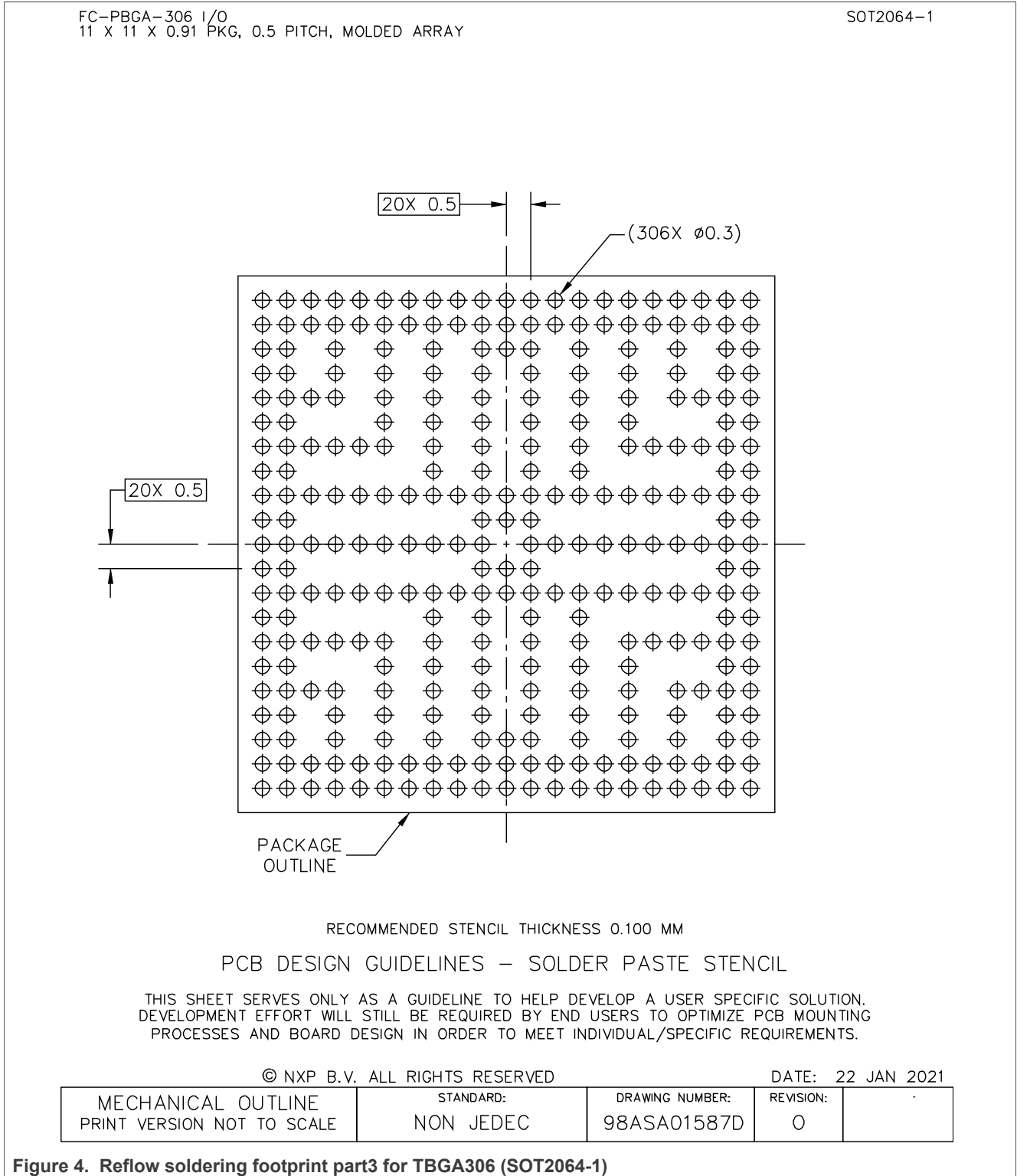


Figure 4. Reflow soldering footprint part3 for TBGA306 (SOT2064-1)

TBGA306, thin ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 0.91 mm body, molded array

FC-PBGA-306 I/O  
11 X 11 X 0.91 PKG, 0.5 PITCH, MOLDED ARRAY

SOT2064-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 22 JAN 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01587D	REVISION: 0	
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Figure 5. Package outline note TBGA306 (SOT2064-1)

## 4 Legal information

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